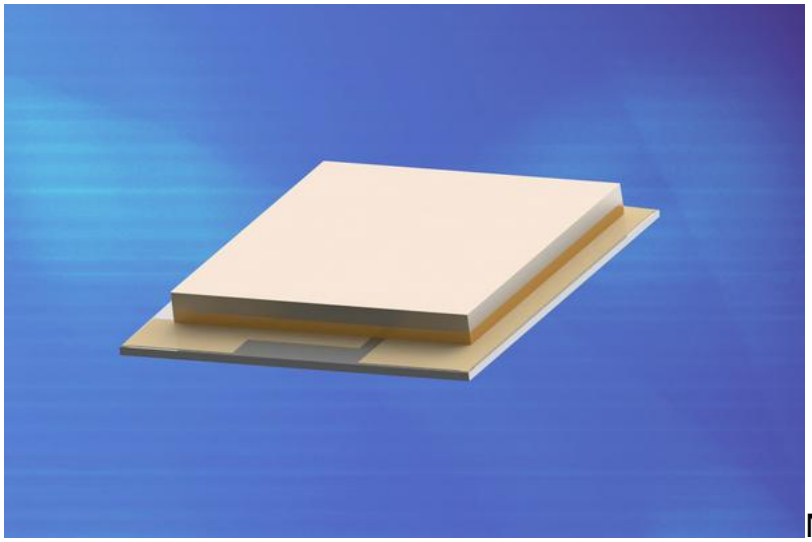
Thin-film thrmoelectric modules offer low-profile thermal solutions



Nextreme Thermal Solutions announced a new series of thin-film thermoelectric modules that offer higher cooling capacity, robust mechanical design and source-matched heat flux density for easier integration into existing electronic systems. At only 1.1mm high, the new eTEC MA8000 series is designed to provide low-profile thermal management solutions for medium heat flux applications in photonics, electronics, and aerospace markets.

The MA8000 series includes five new modules that can pump from 10 to over 80 watts of heat at an ambient temperature of 25°C with footprints ranging from 63 to 375 mm². With heat flux densities ranging from 16 W/cm^2 to 22 W/cm^2, the MA series offers the ability to match thermoelectric cooling designs more easily to heat sources and existing convection-based heat rejection systems. The new modules fill the gap between traditional thermoelectrics that offer 6-8 W/cm^2 and Nextreme's HV series that pumps heat in excess of 100 W/cm^2.

The MA8000 series features a high strength seal ring made from Cirlex® polyimide film that provides mechanical isolation across the thermoelectric device, virtually eliminating vertical force and sheer issues. The seal ring also serves as a barrier to moisture and other contaminants that could affect the performance of the module

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